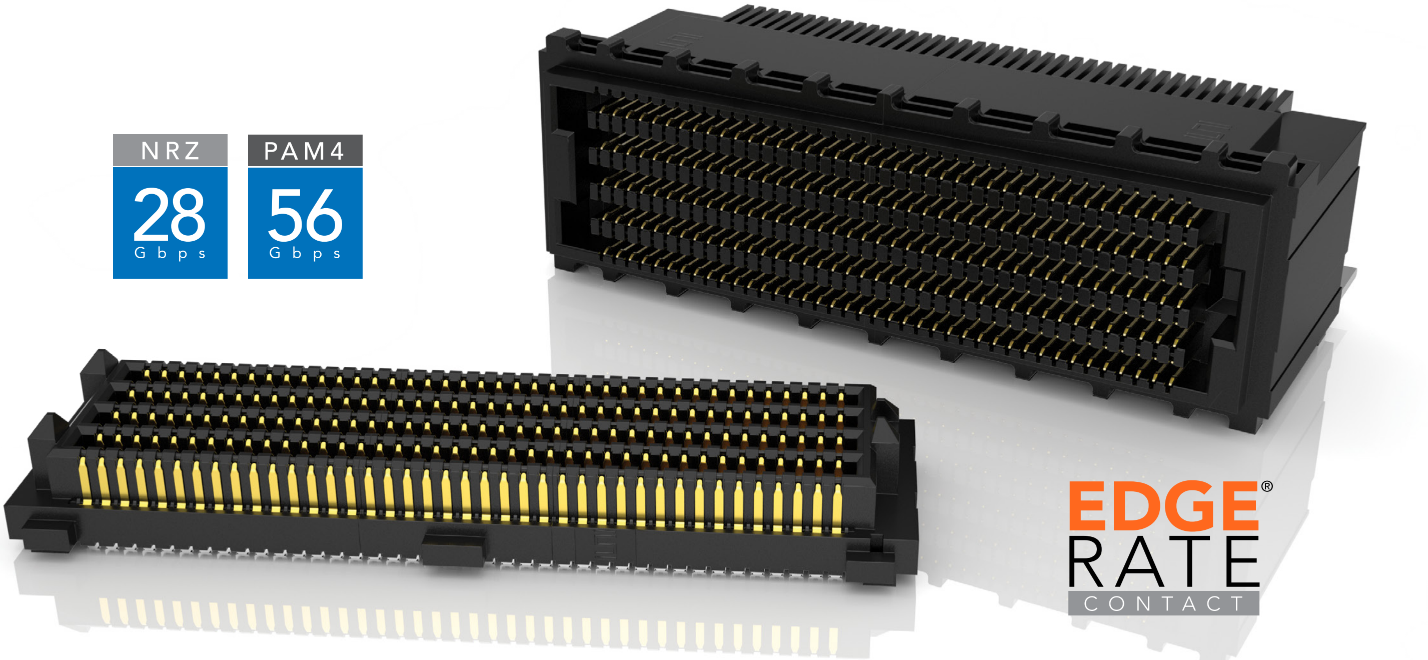
SEARAY™ .8mm

ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

(0.80 mm) .0315" PITCH



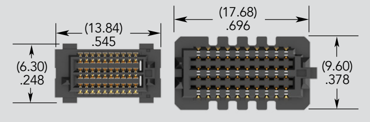
NRZ
28
Gbps

PAM4
56
Gbps

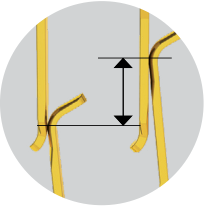
EDGE® RATE CONTACT

FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate® contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces
- Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302. Visit **samtec.com/set**

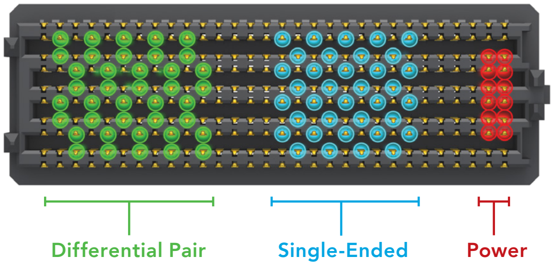


0.80 mm pitch vs. 1.27 mm pitch
(60 pins shown)



(1.12 mm) .044"
Nominal Wipe

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



KEY SPECIFICATIONS (SEAF8/SEAM8)

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM8	Black LCP	Copper Alloy	Au or Sn over 50 µ" (1.27 µm) Ni	–55 °C to +125 °C	1.3 A per pin (10 adjacent pins powered)	220 VAC/311 VDC	Yes
SEAF8							
SEAF8-RA					1.1 A per pin (10 adjacent pins powered)	240 VAC/339 VDC	

(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

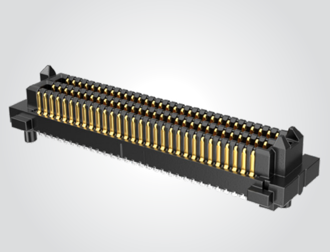
SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal **SEAF8** Socket	**–10, –20, –30, –40, –50**	**–S02.0** = 2 mm Body Height (SEAM8 only) **–S05.0** = 5 mm Body Height (SEAM8 only) **–05.0** = 5 mm Body Height (SEAF8 only)	**–L** = 10 µ" (0.25 µm) Gold on contact area, Matte Tin on solder tail **–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on solder tail **–STL** = 30 µ" (0.76 µm) Gold on contact, Tin/Lead on solder tail (–1 solder type only)	**–04** **–06** **–08** **–10**	**–1** = Tin/Lead Alloy Solder Crimp (–STL only) **–3** = Lead-Free Solder Crimp	**–GP** = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel. **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SEAM8

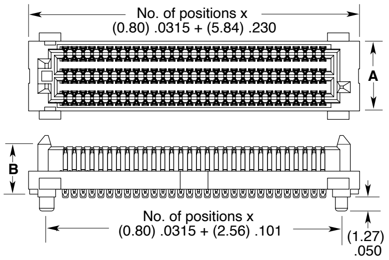
Board Mates:
SEAF8

Cable Mates:
ESCA

Standoffs:
JSO



LEAD STYLE	B
-S02.0	(4.54) .179
-S05.0	(7.54) .297



NO. OF ROWS	A
–04	(4.30) .169
–06	(6.30) .248
–08	(8.30) .327
–10	(10.30) .406

View complete specifications at: samtec.com?SEAM8

MATED HEIGHTS*

SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

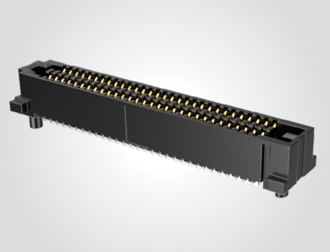
*Processing conditions will affect mated height.

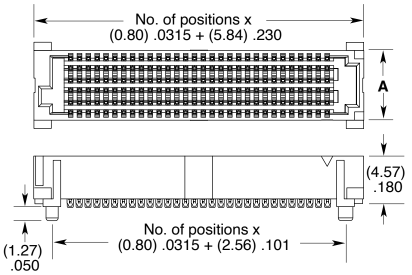
SEAF8

Board Mates:
SEAM8

Cable Mates:
ESCA

Standoffs:
JSO





View complete specifications at: samtec.com?SEAF8

Notes:
Polyimide Pick & Place Pad standard without specifying –K.

Severe Environment Testing qualified; aligns with MIL-DTL-55302. Visit samtec.com/set

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
	–20, –30, –40, –50		**–S** = 30 µ" (0.76 µm) Gold on contact area, Matte Tin on solder tail	**–04** (–50 positions only) **–08** **–10**	**–2** = Lead-Free Solder Crimp		**–GP** = Guide Post Holes	Tape & Reel is standard. Leave blank for Tape & Reel. **–FR** = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

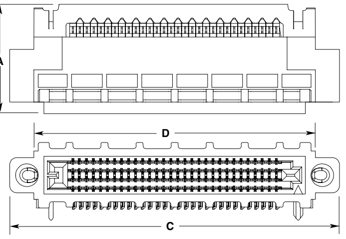
SEAF8-RA

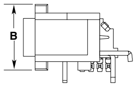
(Right-angle)

Board Mates:
SEAM8

Cable Mates:
ESCA

NO. OF ROWS	A	B
–04	(12.48) .491	(7.46) .294
–08	(16.48) .649	(11.46) .451
–10	(18.48) .728	(13.46) .530





NO. PINS PER ROW	C	D
-20	(29.62) 1.166	(24.12) .950
-30	(37.62) 1.481	(32.12) 1.265
-40	(45.62) 1.796	(40.12) 1.580
-50	(53.62) 2.111	(48.12) 1.894

Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?SEAF8-RA